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(54) **ULTRASOUND TRANSDUCER UNIT AND
ULTRASOUND ENDOSCOPE**

2006/0241467 A1* 10/2006 Takeda et al. 600/459
2008/0089181 A1* 4/2008 Adachi et al. 367/189
2008/0119738 A1* 5/2008 Imahashi et al. 600/462

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FOREIGN PATENT DOCUMENTS

EP 1 498 071 A1 1/2005
JP 2001-333494 11/2001
JP 2003-033354 2/2003
JP 2004-290273 10/2004
JP 2006-025892 2/2006
JP 2008-289910 12/2008

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(Continued)

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filed on Apr. 3, 2012.

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A61B 8/14 (2006.01)

(52) **U.S. Cl.**
USPC **600/459**; 600/437; 310/311

(58) **Field of Classification Search**
USPC 600/437-472; 310/311
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2004/0073118 A1* 4/2004 Peszynski et al. 600/459
2006/0058676 A1 3/2006 Yagi et al.

OTHER PUBLICATIONS

Light, E.D., et al. "New Fabrication Techniques for Ring-Array
Transducers for Real-Time 3D Intravascular Ultrasound", Ultrasonic
Imaging 31, Oct. 1, 2009, pp. 247-256.

(Continued)

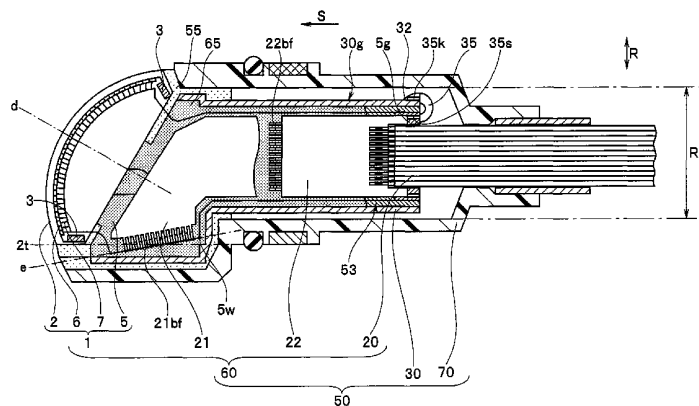
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(57) **ABSTRACT**

An ultrasound transducer unit includes: an ultrasound element; a substrate; a signal transmission cable; a cylindrical metal shield member that has a large-diameter portion, a small-diameter portion, and a step portion, in which the large-diameter portion covers an outer circumference of the substrate; ground wiring that electrically connects the substrate and an outer circumferential face of the metal shield member; and an opening portion formed in the step portion or the small-diameter portion. The ground wiring is extended to outside the metal shield member from inside the large-diameter portion through the opening portion, and is electrically connected to an outer circumferential face of the small-diameter portion to thereby electrically connect the substrate and the outer circumferential face of the metal shield member.

3 Claims, 14 Drawing Sheets



(56)

References Cited

FOREIGN PATENT DOCUMENTS
JP 2009-165509 7/2009
WO 99/24967 A1 5/1999
WO WO 03/086196 A1 10/2003
WO WO 2004/084734 A1 10/2004

WO WO 2009/137403 A1 11/2009

OTHER PUBLICATIONS

European Search Report dated Jun. 17, 2013 from corresponding
European Application No. 12 78 5538.5.

* cited by examiner

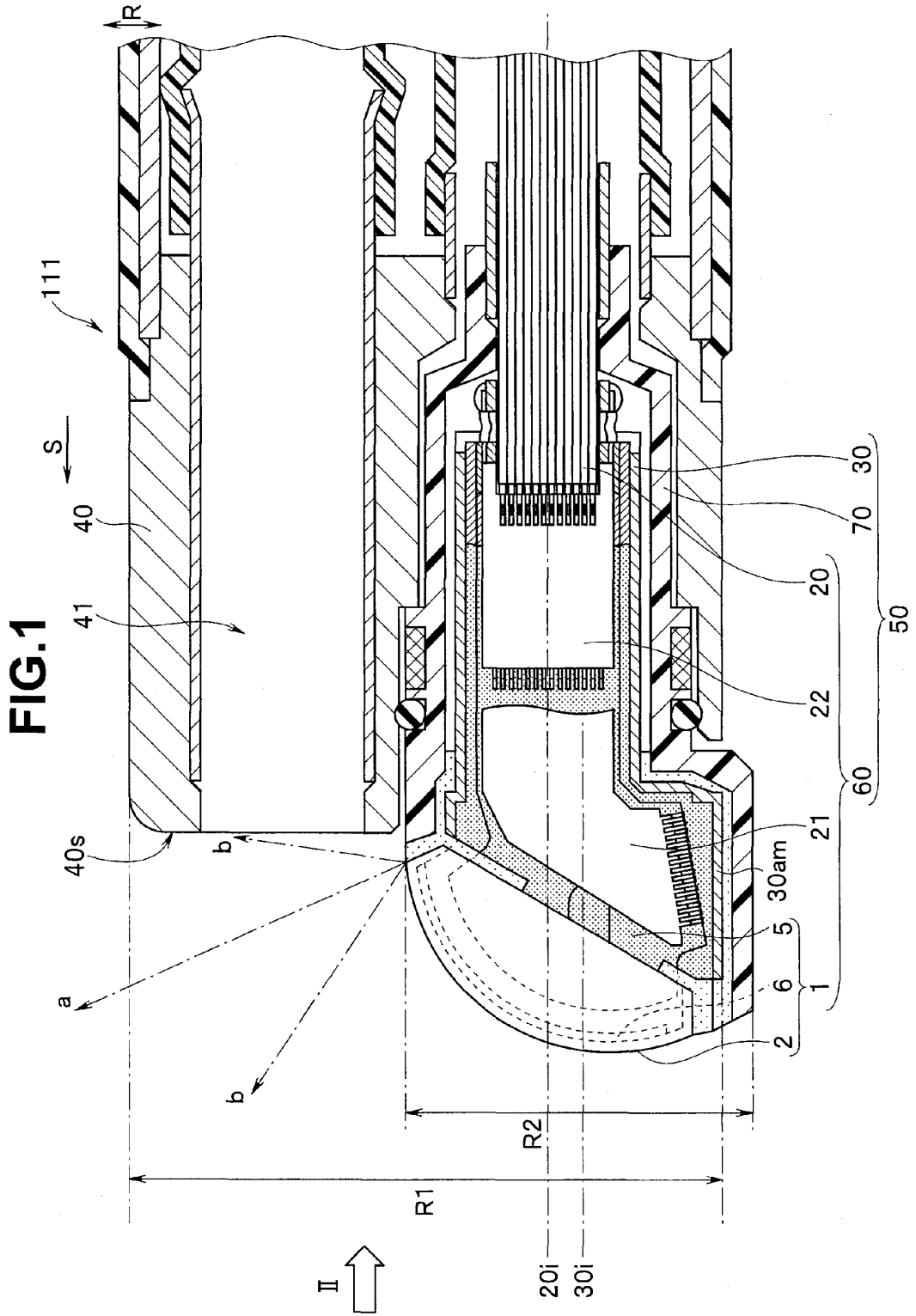


FIG.2

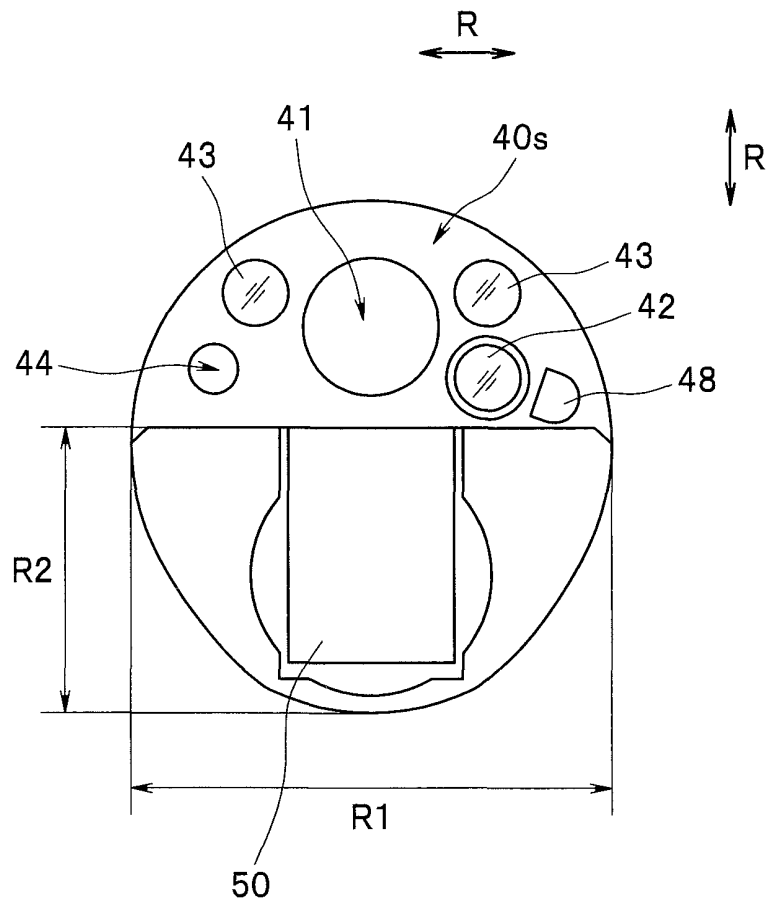


FIG. 3

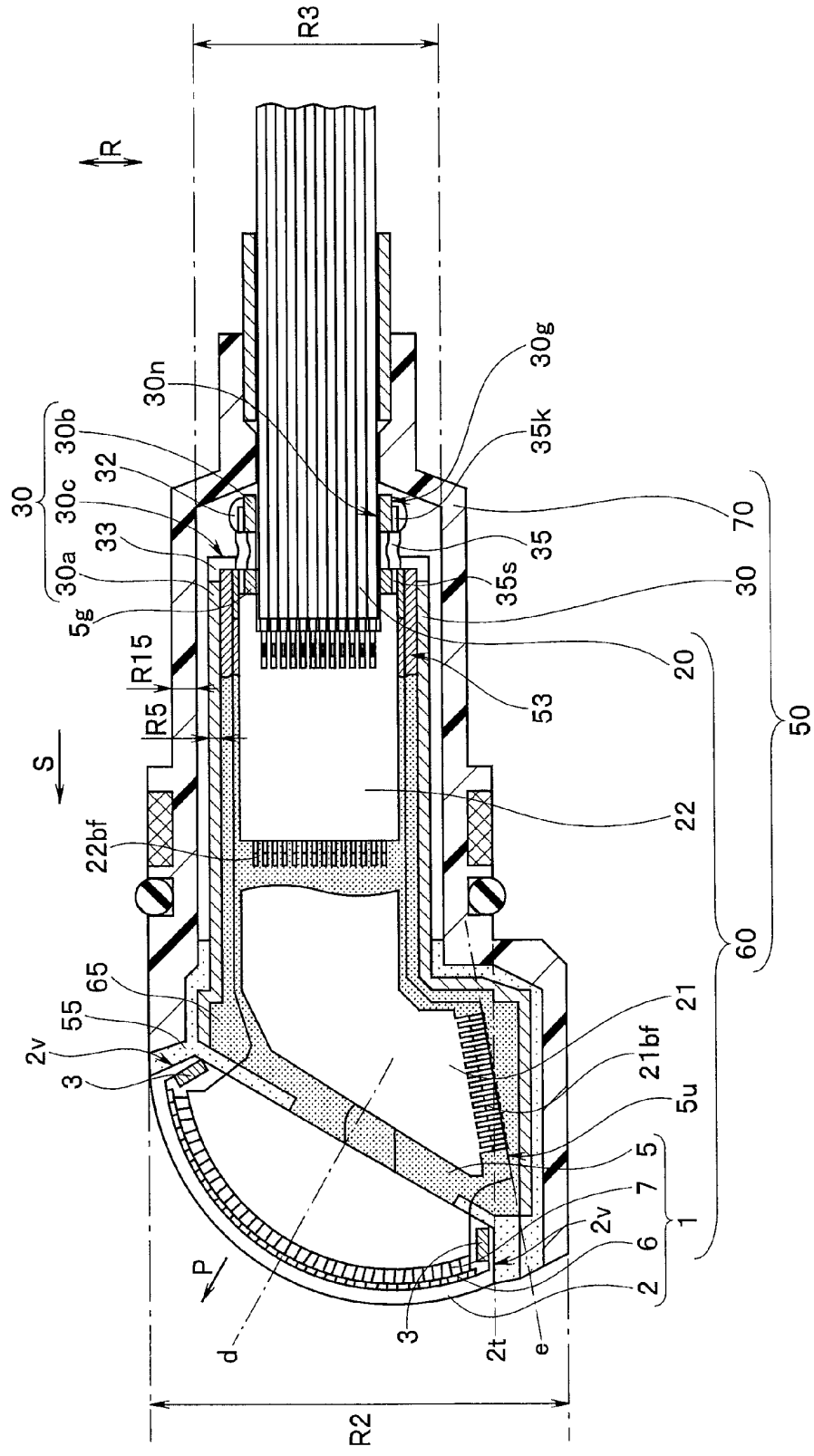


FIG.4

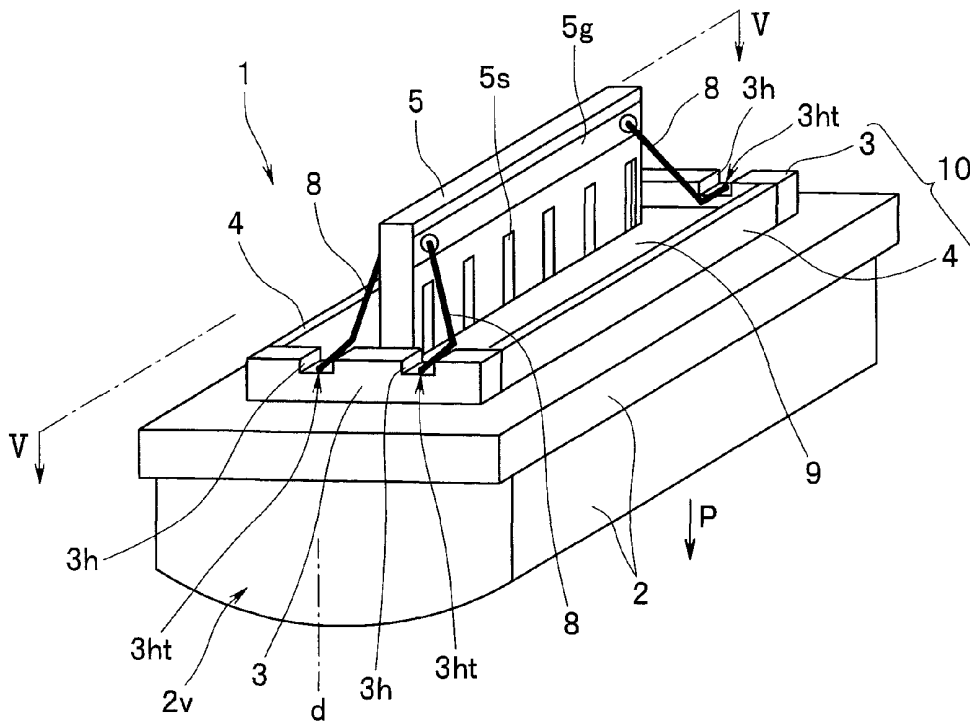


FIG.5

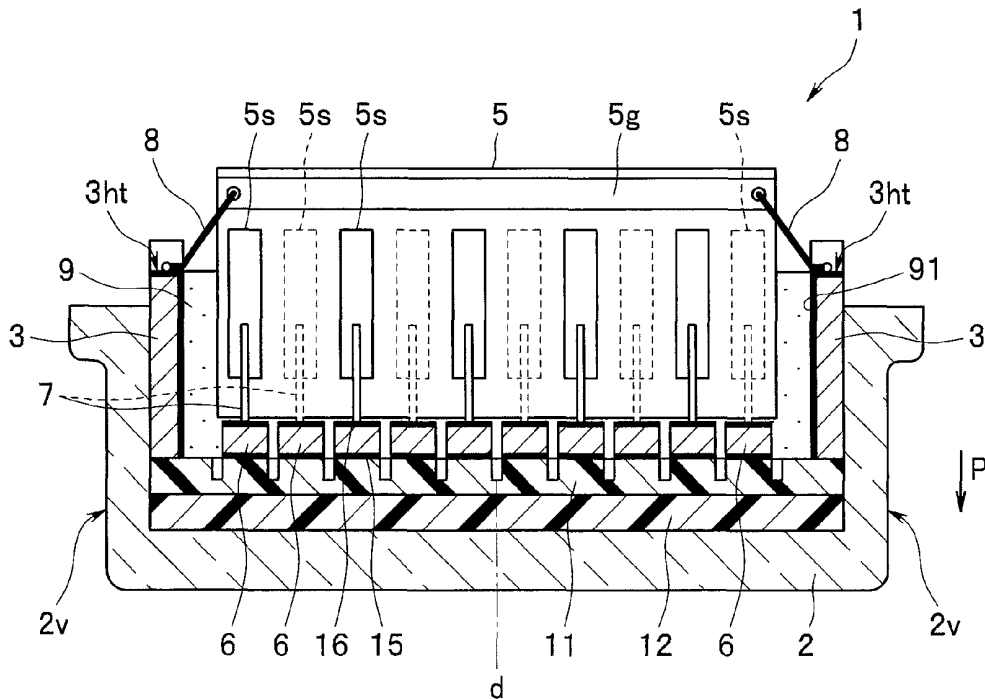


FIG.6

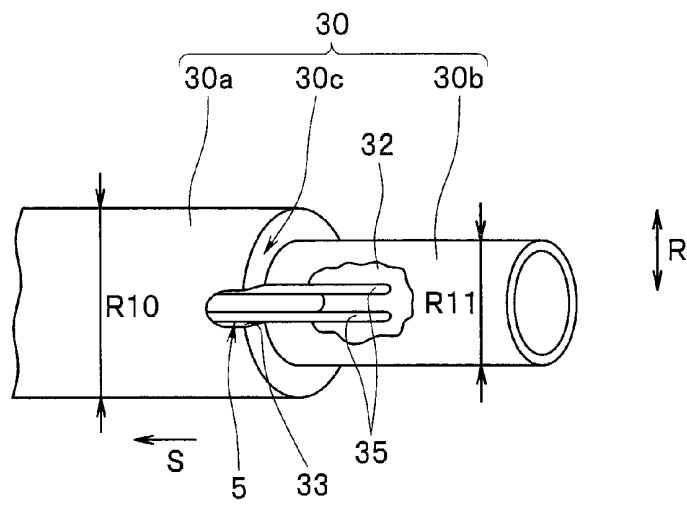


FIG.7

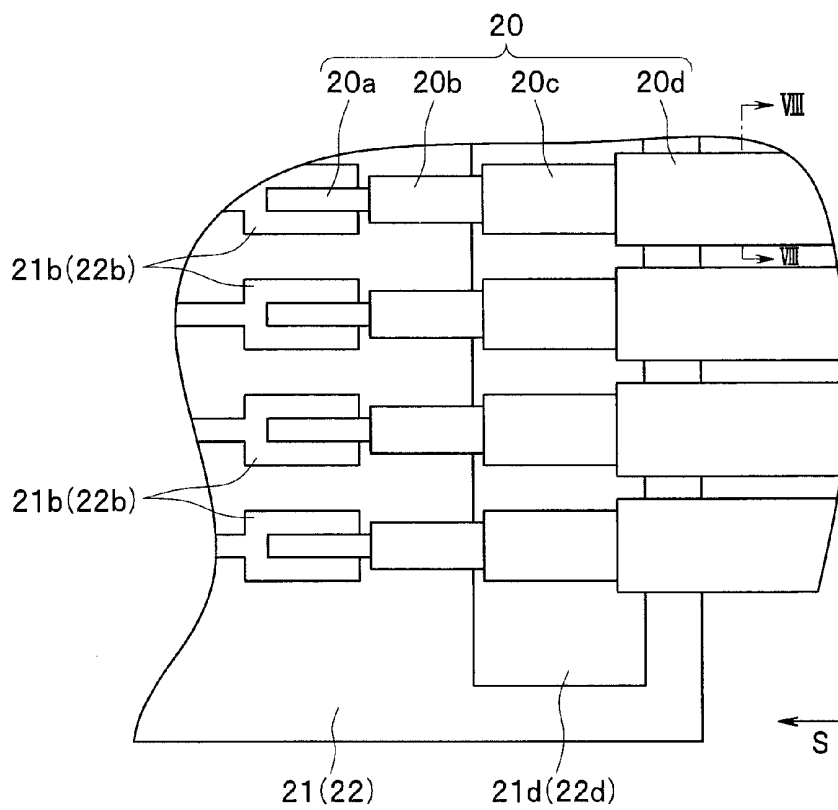


FIG.8

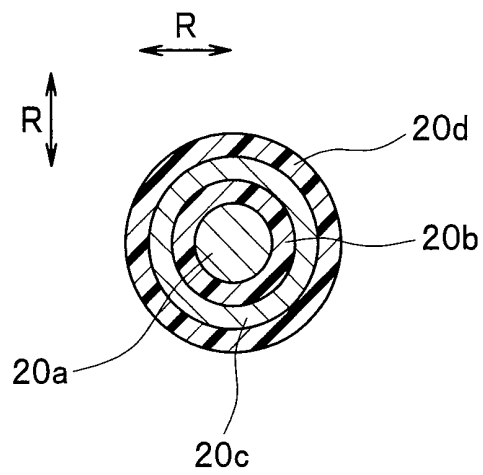


FIG.9

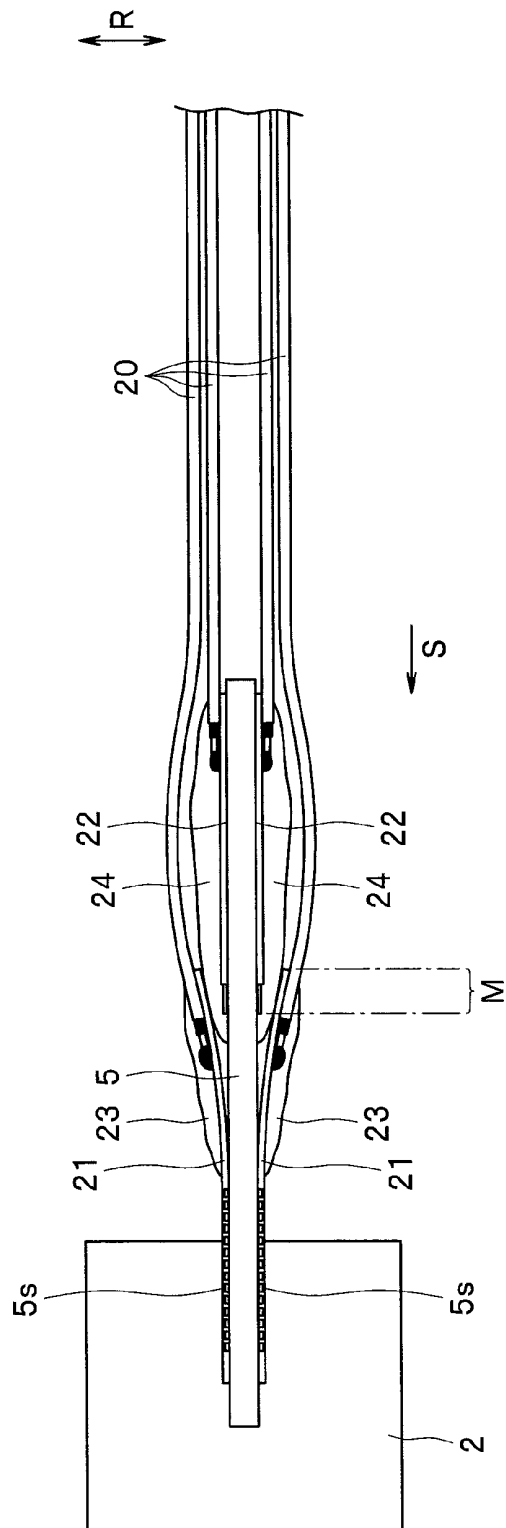


FIG. 10

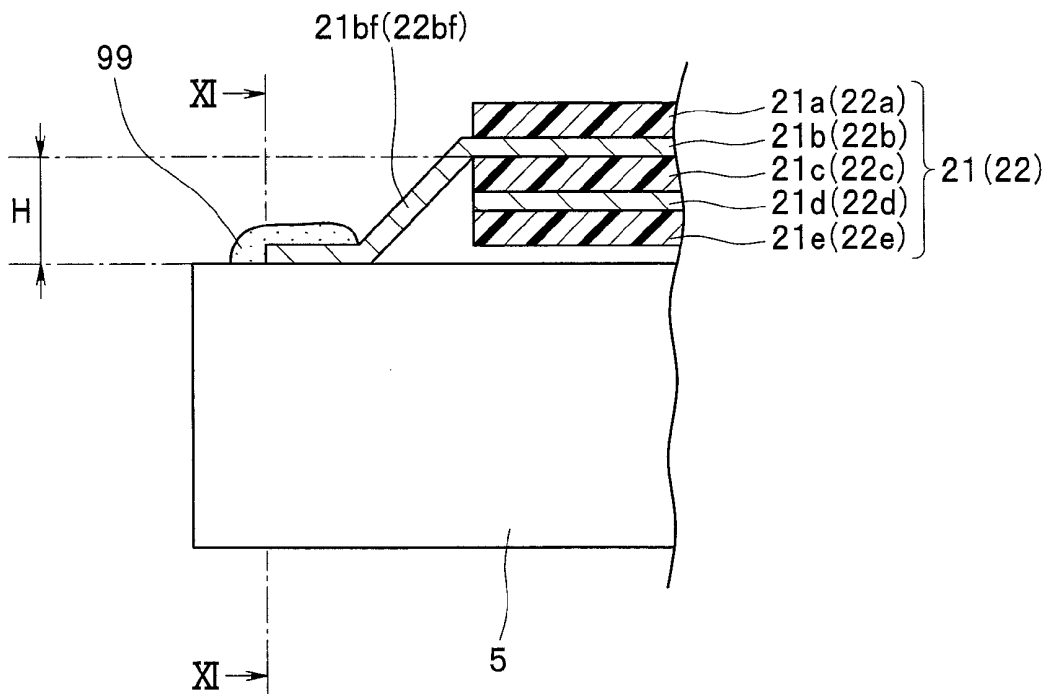


FIG.11

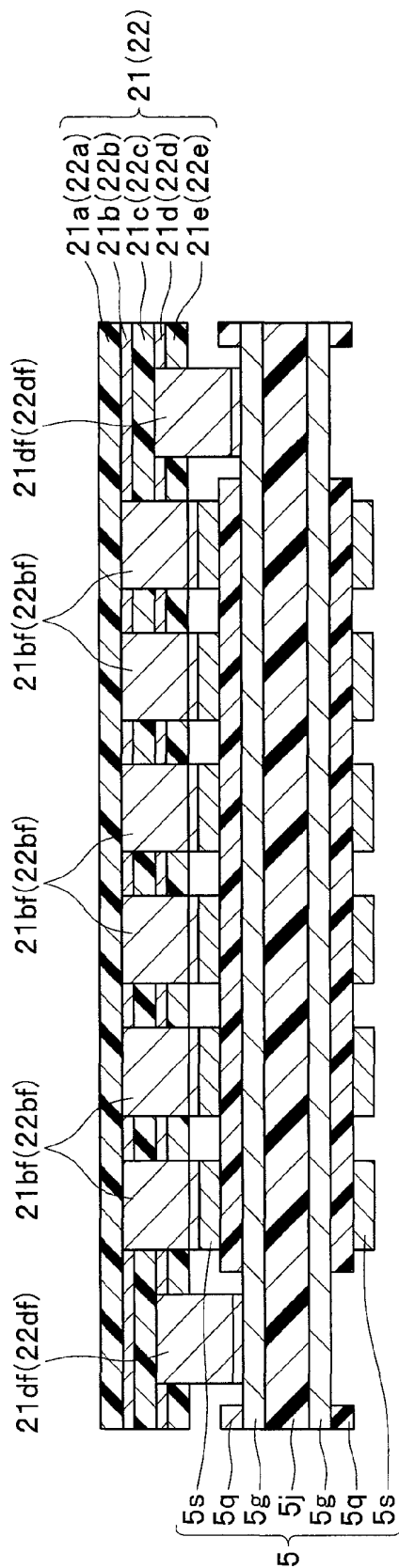


FIG.12

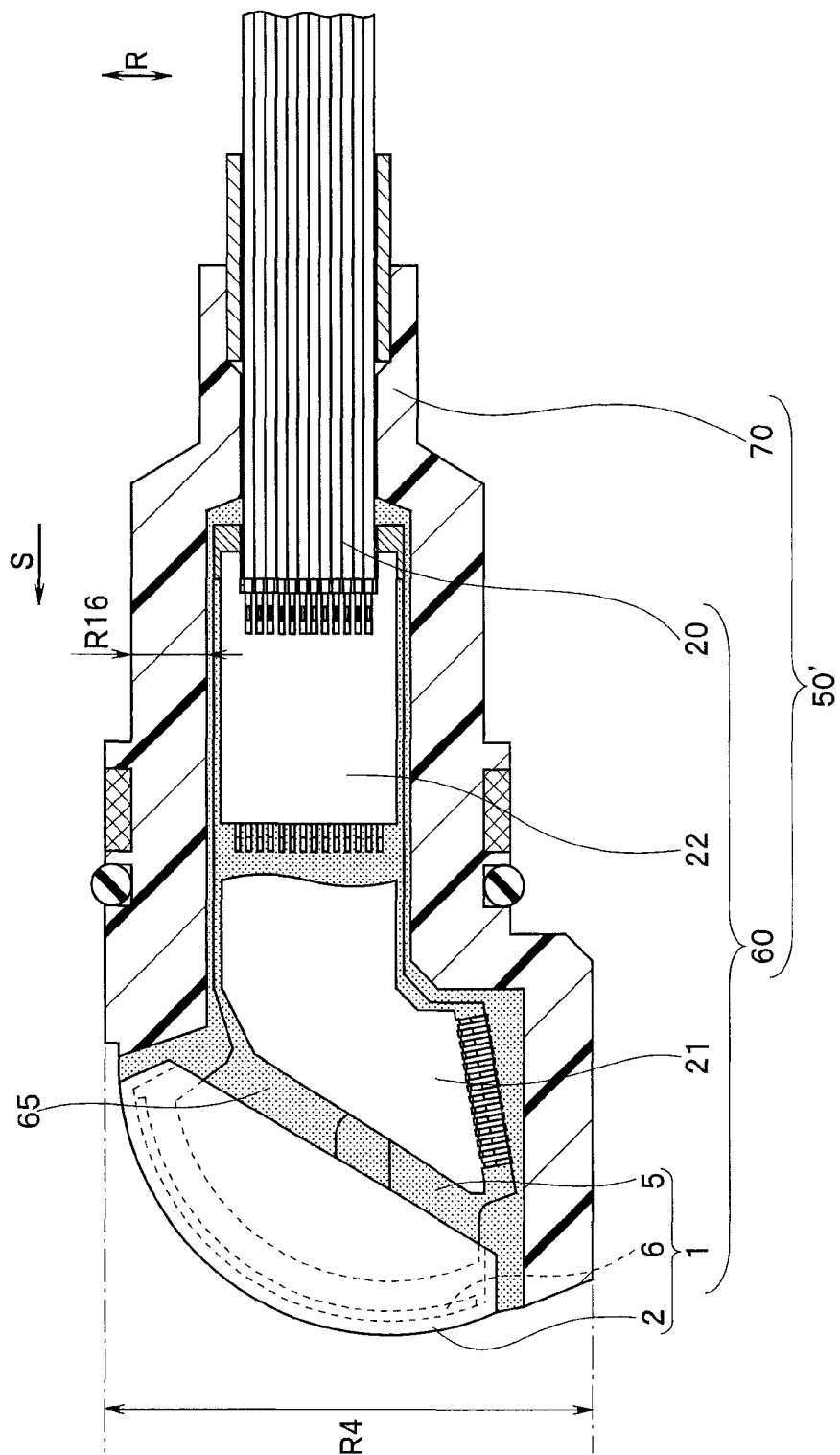


FIG. 13

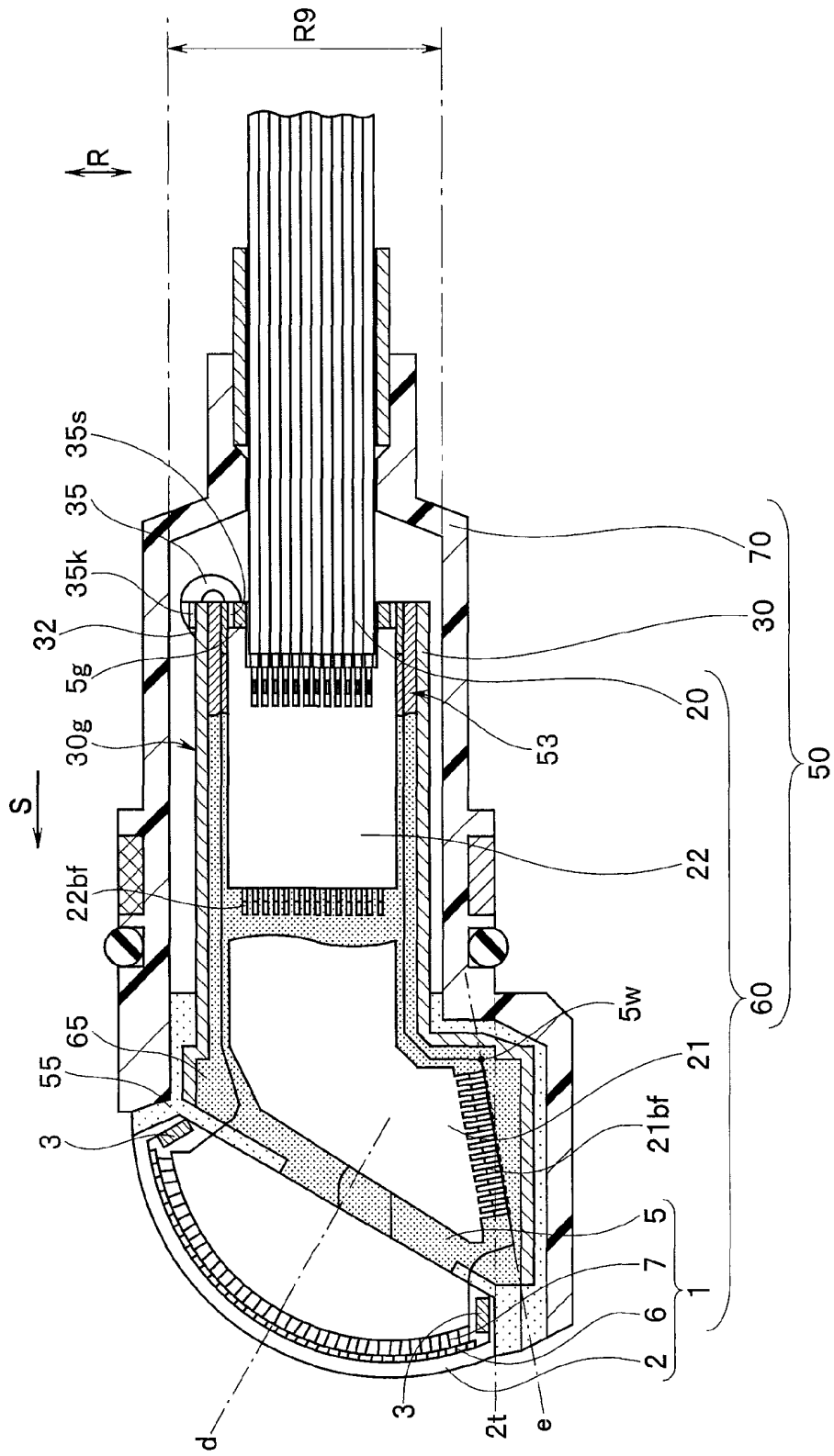


FIG.14

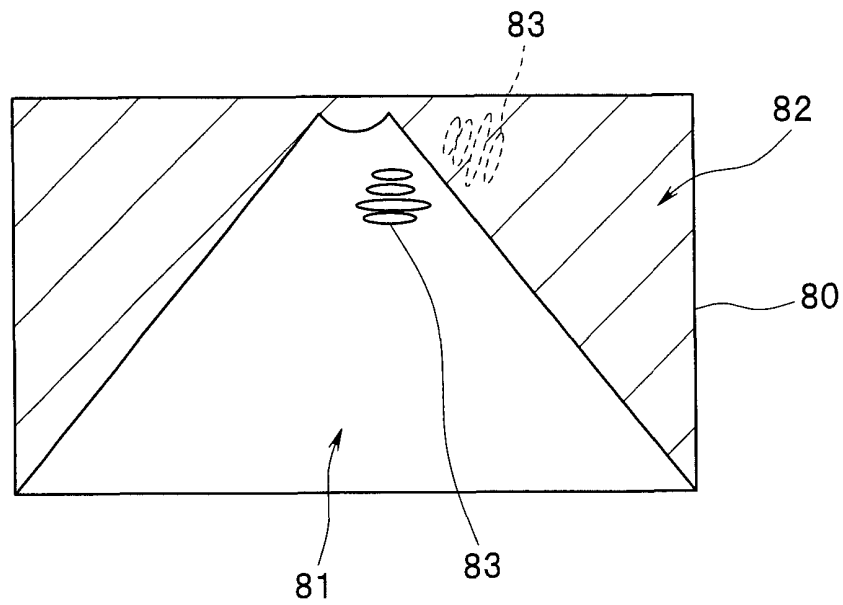


FIG. 15

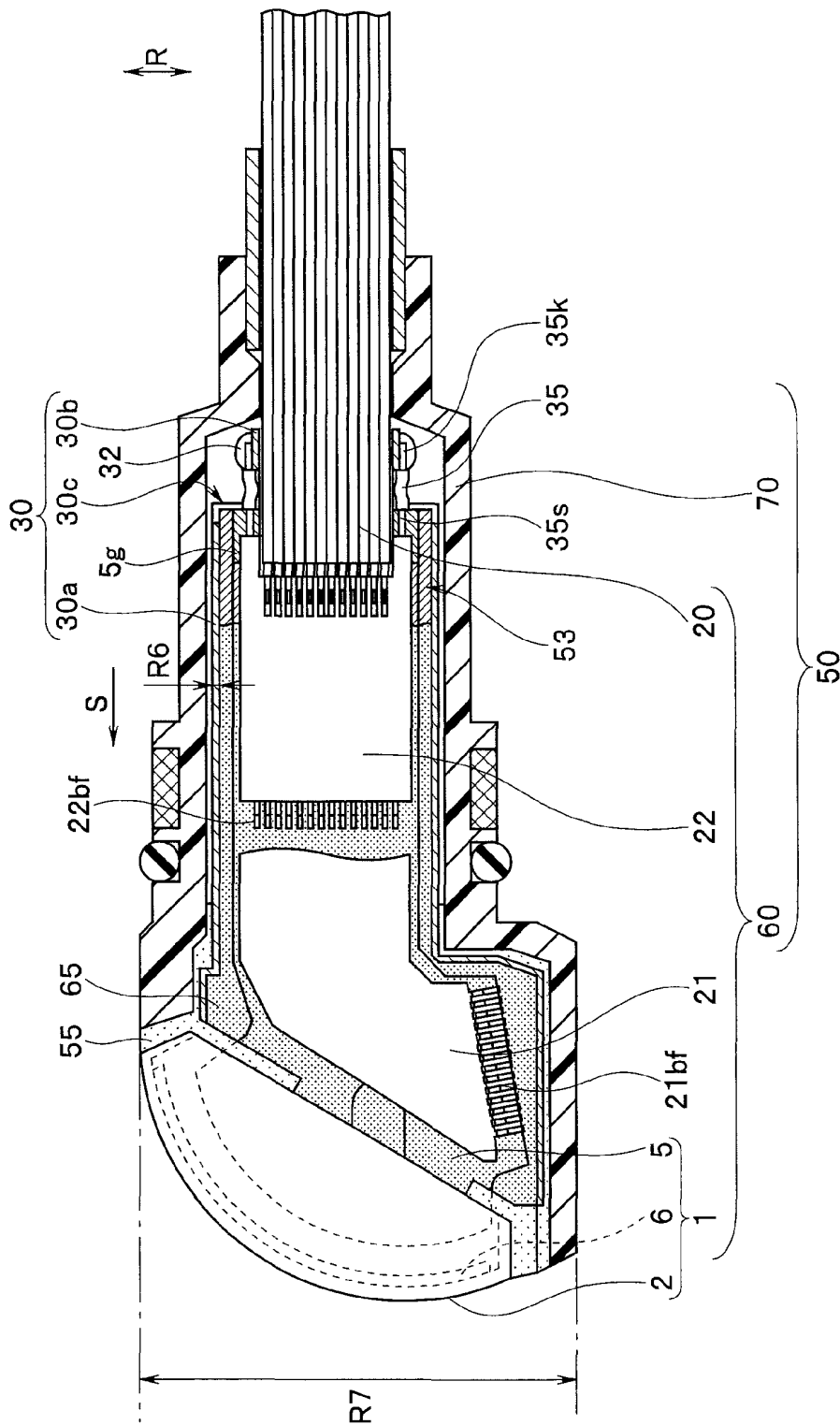
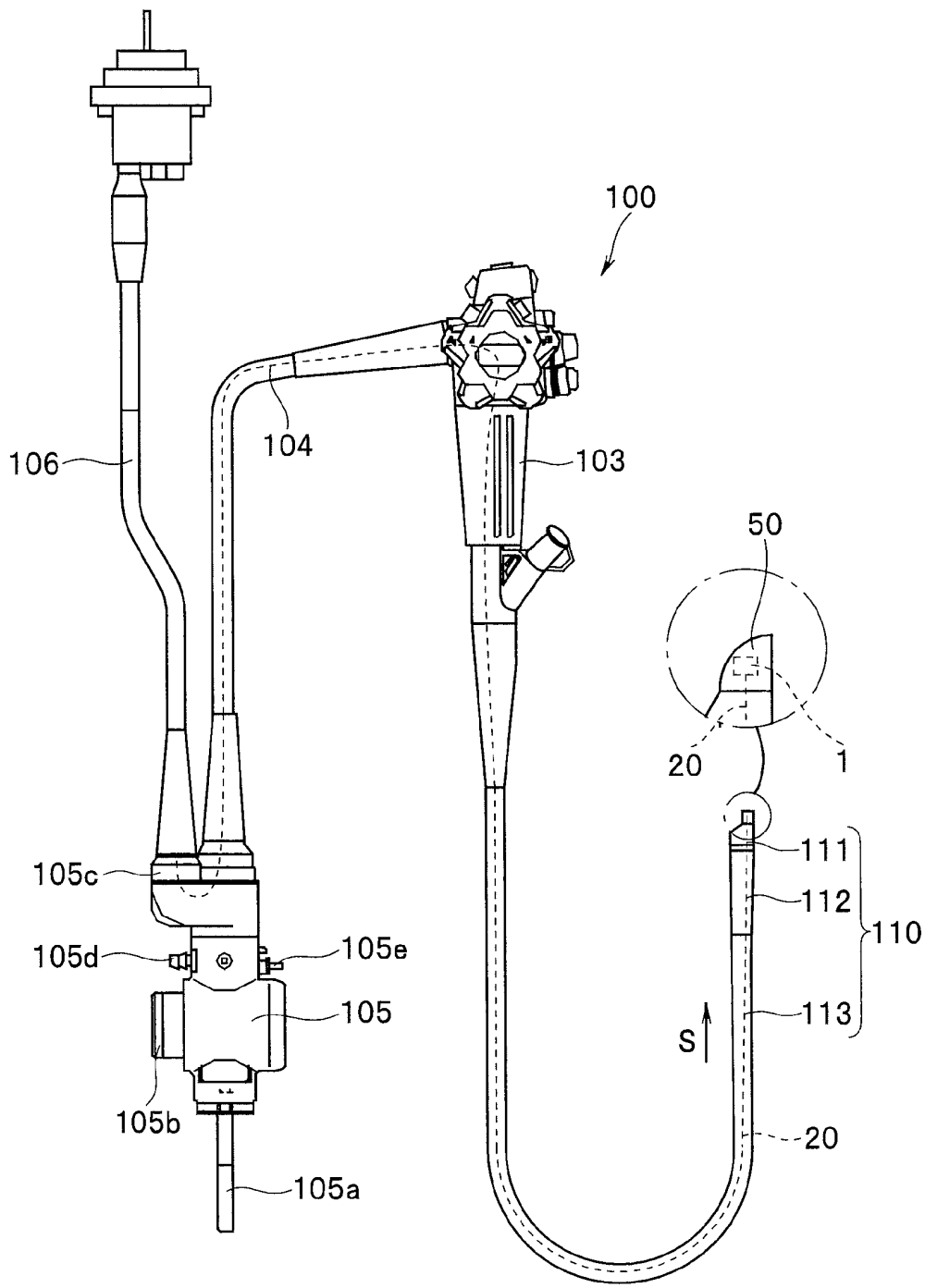


FIG. 16



ULTRASOUND TRANSDUCER UNIT AND ULTRASOUND ENDOSCOPE

CROSS REFERENCE TO RELATED APPLICATION

This application is a continuation application of PCT/JP2012/059098 filed on Apr. 3, 2012 and claims benefit of Japanese Application No. 2011-108510 filed in Japan on May 13, 2011, the entire contents of which are incorporated herein by this reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to an ultrasound transducer unit and an ultrasound endoscope equipped with a metal shield member that covers an outer circumference of a substrate that electrically connects an ultrasound element and a signal transmission cable.

2. Description of the Related Art

In an ultrasound endoscope with which it is possible to observe an ultrasound image that is a two-dimensional visible image of a site to be examined, an ultrasound transducer that is provided on a distal end side of an insertion portion normally has a configuration that includes a GND electrode provided on a top face of an ultrasound element such as a single-plate piezoelectric element, and a signal electrode provided on a bottom face of the ultrasound element. The ultrasound transducer has a function that, by application of a voltage from outside to the electrodes on the top and bottom faces of the ultrasound element, radiates ultrasound that accompanies vibration of the ultrasound element towards a site to be examined, and receives a reflected acoustic wave from the site to be examined and converts the reflected acoustic wave into an electrical signal.

Further, a configuration is known in which transferring of at least electric power and electrical signals between the ultrasound transducer and an external device is performed through a signal transmission cable that is inserted through the inside of an insertion portion of the ultrasound endoscope and is electrically connected to the signal electrode of the ultrasound element, within a transducer case that holds the ultrasound transducer.

Note that the signal transmission cable includes a plurality of cables in which the electrical safety is ensured by providing a signal wire and a GND wire that is positioned on an outer layer of the signal wire on the same axis.

In this case, a configuration is also known in which electrical connection of a signal transmission cable to an ultrasound element is performed through a substrate, as disclosed, for example, in Japanese Patent Application Laid-Open Publication No. 2006-25892.

Further, since it is necessary from the viewpoint of electrical safety to also securely cover an exposed area of an electrode in the substrate or the ultrasound element, such as an electrode to which the signal transmission cable is connected in the substrate and an electrode to which the substrate is connected in the ultrasound element, in Japanese Patent Application Laid-Open Publication No. 2006-25892 a configuration is disclosed in which, inside a transducer case that holds an ultrasound transducer, the substrate is hermetically sealed and covered from outside using a metal shield member that is grounded.

Note that, hereunder, a structure in which a metal shield member is covered over the outside of a substrate in a state in

which a signal transmission cable is electrically connected to the substrate inside a transducer case is referred to as an "ultrasound transducer unit."

As a configuration for grounding a metal shield member, a configuration is known in which the other end of ground wiring having one end electrically connected to a GND pattern provided on a substrate inside the metal shield member is led out to outside of the metal shield member from inside the metal shield member through an opening in a rear end of the metal shield member before hermetic sealing is performed, and the aforementioned other end is connected by a solder or the like to an outer circumferential face of the metal shield to thereby perform grounding.

SUMMARY OF THE INVENTION

An ultrasound transducer unit according to one aspect of the present invention includes: an ultrasound element; a substrate having one end that is electrically connected to the ultrasound element; a signal transmission cable that is electrically connected to the other end of the substrate; a cylindrical metal shield member that has a large-diameter portion, a small-diameter portion that has a smaller diameter than a diameter of the large-diameter portion, and a step portion that connects the large-diameter portion and the small-diameter portion, in which an opening portion is formed in the step portion or the small-diameter portion, and in which the large-diameter portion covers an outer circumference of the substrate; and ground wiring that electrically connects the substrate and an outer circumferential face on an opposite side to an inner surface that faces the substrate of the metal shield member; wherein the ground wiring electrically connects the substrate and the outer circumferential face of the metal shield member by being extended to outside the metal shield member from inside the large-diameter portion of the metal shield member through the opening portion and electrically connected to the outer circumferential face of the small-diameter portion.

Further, an ultrasound endoscope according to another aspect of the present invention includes the ultrasound transducer unit according to claim 1 at a distal end in an insertion direction of an insertion portion that is inserted into a subject.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a partial cross-sectional view showing a distal end side of an insertion portion of an ultrasound endoscope including an ultrasound transducer unit according to an embodiment of the present invention;

FIG. 2 is a front view of the distal end of the insertion portion shown in FIG. 1 as viewed from a direction II in FIG. 1;

FIG. 3 is a partial cross-sectional view that illustrates the ultrasound transducer unit shown in FIG. 1 in an enlarged manner;

FIG. 4 is a perspective view that illustrates the ultrasound transducer shown in FIG. 1 in an enlarged manner;

FIG. 5 is a sectional view of the ultrasound transducer along a line V-V in FIG. 4;

FIG. 6 is a partial enlarged perspective view that illustrates a rear end side of a metal shield member shown in FIG. 1;

FIG. 7 is a view that illustrates a connection of a signal transmission cable to a flexible substrate shown in FIG. 1 in an enlarged manner;

FIG. 8 is a sectional view of a single coaxial line of the signal transmission cable along a line VIII-VIII in FIG. 7;

FIG. 9 is a view that illustrates, in an enlarged manner, a connection of the flexible substrate to which the signal transmission cable is connected, to the substrate that is shown in FIG. 1;

FIG. 10 is a partial cross-sectional view that illustrates the connection of the flexible substrate to the substrate that is shown in FIG. 9 in an enlarged manner;

FIG. 11 is a sectional view of the substrate and the flexible substrate along a line XI-XI in FIG. 10;

FIG. 12 is a partial cross-sectional view that illustrates, in an enlarged manner, an ultrasound transducer unit that has a configuration that does not use a metal shield member;

FIG. 13 is a partial cross-sectional view that illustrates a conventional example in which the other end of ground wiring that has one end connected to a ground wiring land of a substrate is led out to outside a metal shield member from inside the metal shield member through an opening in a rear end of the metal shield member, and connected by a solder or the like to an outer circumferential face of the metal shield member;

FIG. 14 is a view that illustrates an example in which a reflected image of a distal end face is displayed in a display image as the result of a side lobe of ultrasound that is radiated from the ultrasound transducer shown in FIG. 1 being reflected by a distal end face of a distal end portion of an insertion portion;

FIG. 15 is a partial cross-sectional view of an ultrasound transducer unit that illustrates an example in which the metal shield member shown in FIG. 1 is formed to be thinner than in FIG. 1; and

FIG. 16 shows the outer appearance of an ultrasound endoscope in which the ultrasound transducer unit shown in FIG. 3 is provided.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

An embodiment of the present invention is described hereunder with reference to the drawings. It should be noted that the drawings are schematic ones in which the relationship between the thickness and width of each member, the thickness ratios of the members, and the like are different from those of actual members. Naturally, the drawings include portions in which the dimensional relationships and ratios are different from one another.

FIG. 1 is a partial cross-sectional view showing a distal end side of an insertion portion of an ultrasound endoscope including an ultrasound transducer unit according to the present embodiment. FIG. 2 is a front view of the distal end of the insertion portion shown in FIG. 1 as viewed from a direction II in FIG. 1. FIG. 3 is a partial cross-sectional view that illustrates the ultrasound transducer unit shown in FIG. 1 in an enlarged manner.

FIG. 4 is a perspective view that illustrates the ultrasound transducer shown in FIG. 1 in an enlarged manner. FIG. 5 is a sectional view of the ultrasound transducer along a line V-V in FIG. 4. FIG. 6 is a partial enlarged perspective view that illustrates a rear end side of a metal shield member shown in FIG. 1. FIG. 7 is a view that illustrates a connection of a signal transmission cable to a flexible substrate shown in FIG. 1 in an enlarged manner. FIG. 8 is a sectional view of a single coaxial line of the signal transmission cable along a line VIII-VIII in FIG. 7.

FIG. 9 is a view that illustrates, in an enlarged manner, a connection of the flexible substrate to which the signal transmission cable is connected, to the substrate that is shown in FIG. 1. FIG. 10 is a partial cross-sectional view that illustrates

the connection of the flexible substrate to the substrate that is shown in FIG. 9 in an enlarged manner. FIG. 11 is a sectional view of the substrate and the flexible substrate along a line XI-XI in FIG. 10.

FIG. 12 is a partial cross-sectional view that illustrates, in an enlarged manner, an ultrasound transducer unit that has a configuration that does not use a metal shield member. FIG. 13 is a partial cross-sectional view that illustrates a conventional example in which the other end of ground wiring that has one end connected to a ground wiring land of a substrate is led out to outside a metal shield member from inside the metal shield member through an opening in a rear end of the metal shield member, and connected by a solder or the like to an outer circumferential face of the metal shield member.

FIG. 14 is a view that illustrates an example in which a reflected image of a distal end face is displayed in a display image as the result of a side lobe of ultrasound that is radiated from the ultrasound transducer shown in FIG. 1 being reflected by a distal end face of a distal end portion of an insertion portion. FIG. 15 is a partial cross-sectional view of an ultrasound transducer unit that illustrates an example in which the metal shield member shown in FIG. 1 is formed to be thinner than in FIG. 1.

As shown in FIG. 1, a distal end portion 111 that is positioned at a distal end in an insertion direction S of an insertion portion 110 of an ultrasound endoscope 100 (the insertion portion 110 and ultrasound endoscope 100 are shown in FIG. 16) that are described later includes a distal end rigid member 40 that has a size R1 in a diameter direction R.

In the distal end rigid member 40, a distal end side in the insertion direction S of an ultrasound transducer unit 50 and a distal end side in the insertion direction S of a treatment instrument insertion channel 41 are provided along the insertion direction S. Note that the distal end side in the insertion direction S of the ultrasound transducer unit 50 has a diameter R2 in the diameter direction R.

As shown in FIG. 1, the ultrasound transducer unit 50 is provided so that, with respect to the distal end rigid member 40, the distal end thereof in the insertion direction S protrudes forward in the insertion direction S more than a distal end face 40s of the distal end rigid member 40. More specifically, at least an ultrasound element 6 such as a piezoelectric element that is included in an ultrasound transducer 1 is provided so as to protrude forward in the insertion direction S more than the distal end face 40s of the distal end rigid member 40.

An image pickup unit and an illumination unit (neither are shown in the drawings) are provided in the distal end rigid member 40. Further, a distal end side in the insertion direction S of an unshown air/water supply conduit and a forward water supply conduit 44 (see FIG. 2) or the like is provided along the insertion direction S.

In addition, as shown in FIG. 2, an objective optical system 42 that is included in the image pickup unit, and an illumination optical system 43 that is included in the illumination unit are provided in the distal end face 40s. Further, the distal ends in the insertion direction S of the treatment instrument insertion channel 41 and the forward water supply conduit 44 are opened at the distal end face 40s. Furthermore, an air/water supply nozzle 48 or the like that is fixed to the distal end of the air/water supply conduit that supplies a fluid to the objective optical system 42 is provided in the distal end face 40s.

Note that, preferably, the distal end face 40s is made from a material having an acoustic impedance that is substantially equal to the acoustic impedance of water, such as, for example, silicone rubber.

As shown in FIG. 1, in some cases, ultrasound that is radiated towards a site to be examined through acoustic

matching layers **11** and **12** and a lens **2** (see FIG. 5), described later, from the ultrasound element **6** is also radiated in side lobe directions **b** in addition to being radiated in a main lobe direction **a**. Consequently the ultrasound is also radiated towards the distal end face **40s**.

Hence, if the acoustic impedance value of the material that the distal end face **40s** is made of differs significantly from the acoustic impedance value of water, that is, the acoustic impedance value of a site in a living body as a site to be examined, ultrasound that is radiated in the side lobe directions **b** is liable to be reflected by the distal end face **40s**, and unwanted scanning signals will be inputted to each ultrasound element **6**. As a result, as shown in FIG. 14, there is the possibility that, on a display apparatus, a reflected image **83** which is normally not displayed because the reflected image **83** appears in a non-display region **82**, will be displayed on the display apparatus as a virtual image in a display region **81** as the result of a known grating lobe after image processing.

Therefore, if the distal end face **40s** is made from a material having an acoustic impedance that is substantially equal to water, that is, a living body, as shown in FIG. 14, it is possible to suppress the display of the reflected image **83** as a virtual image in the display region **81**.

The above described situation is not limited to the distal end face **40s**, and it is also preferable that in the distal end rigid member **40**, an area at which ultrasound that is radiated in the side lobe directions **b** is reflected is made from a material having an acoustic impedance that is substantially equal to that of water.

Further, when a cover is covered over an outer surface of the distal end rigid member **40**, it is preferable that the cover itself is made from a material having an acoustic impedance that is substantially equal to that of water.

As shown in FIG. 1, the ultrasound transducer unit **50** includes the ultrasound transducer **1**. As shown in FIG. 4 and FIG. 5, the principal components of the ultrasound transducer **1** include the lens **2**, a backing material frame **10**, a substrate **5**, a plurality of ultrasound elements **6**, GND electrodes **15**, signal electrodes **16**, and acoustic matching layers **11** and **12**.

More specifically, in the ultrasound transducer **1**, the backing material frame **10** is provided on the inner side of the lens **2**. Note that the backing material frame **10** is formed with, for example, glass epoxy resin.

The backing material frame **10** is formed in a frame shape by two facing end boards **3** and two facing side boards **4** so that the shape thereof in a plan view is rectangular. A rear end side in an ultrasound radiation direction **P** is positioned so as to protrude from the inside of the lens **2**.

As shown in FIG. 3, it is preferable that each end board **3** is slantingly provided relative to a central axis **d** in the array direction of the ultrasound elements **6** so that a rear end side thereof in the ultrasound radiation direction **P** inclines to the inner side.

This is because, as shown in FIG. 4 and FIG. 5, in a case where each end board **3** is provided in parallel with the central axis **d** in the array direction, the diameter of the ultrasound transducer **1** will increase in the diameter direction **R** as the central axis **d** in the array direction inclines so as to become parallel to the insertion direction **S**. Furthermore, in comparison to a case where each end board **3** is provided in parallel with the central axis **d** in the array direction, when a configuration is adopted in which each end board **3** is slantingly provided as shown in FIG. 3, an outer diameter of the backing material frame **10** decreases towards the rear in the ultrasound radiation direction **P**. As a result, the diameter of the distal end side in the insertion direction **S** of the ultrasound transducer unit **50** in the diameter direction **R** can be reduced.

Hence, by adopting a configuration in which, in conformity with the end boards **3**, both end faces **2v** of the lens **2** are also formed in a shape that inclines so as to be parallel to the end boards **3**, for the same reasons as for the backing material frame **10**, it is possible to make the diameter of the distal end side in the insertion direction **S** of the ultrasound transducer unit **50** in the diameter direction **R** smaller in conformity with the inclination of the end boards **3**.

A distal end side in the ultrasound radiation direction **P** of the substrate **5** is inserted through the inside of the backing material frame **10**. A backing material **9** is filled inside the backing material frame **10** so as to cover the outer circumference of the distal end side in the ultrasound radiation direction **P** of the substrate **5**.

A plurality of signal wiring lands **5s** and GND wiring lands **5g** are formed on both surfaces that face the side boards **4** of the substrate **5**.

More specifically, as shown in FIG. 11, the substrate **5** is formed of seven layers that include a first resin layer **5j**, GND wire layers **5g** constituting GND wiring lands that are formed on both faces of the first resin layer **5j**, second resin layers **5q** formed on faces on an opposite side to the first resin layer **5j** of each GND wire layer **5g**, and signal wire layers **5s** constituting signal wiring lands that are formed on faces on an opposite side to the respective GND wire layers **5g** of each second resin layer **5q**.

Note that a plurality of the signal wire layers **5s** are provided with a predetermined interval therebetween in a direction that is orthogonal to the direction in which the layers are formed on each other.

The GND wiring lands are formed at areas that are exposed from the second resin layer **5q** in the GND wire layer **5g**.

Each signal wiring land **5s** of the substrate **5** is electrically connected to each signal electrode **16** provided on a face on a substrate **5** side of the plurality of ultrasound elements **6** through signal wiring wires **7** inside the backing material **9**, respectively.

Note that connection portions between each signal wiring land **5s** and each signal wiring wire **7** and connection portions between the signal electrodes **16** and each signal wiring wire **7** are covered by an unshown metal frame that is grounded to ensure electrical safety.

The ultrasound elements **6** are formed by firing a piezoelectric material, for example, ceramic, and are arranged, for example, in a convex shape.

The ultrasound elements **6** irradiate ultrasound through the acoustic matching layers **11** and **12** and the lens **2** at a site to be examined, and also receive acoustic waves that are reflected from the site to be examined.

Inside the lens **2**, the GND electrodes **15** that have been subjected to a poling process are respectively provided on a front side in the ultrasound radiation direction **P** of each ultrasound element **6**.

The GND electrodes **15** and the signal electrodes **16** cause the ultrasound elements **6** to vibrate by applying a pulse voltage that is transmitted through a signal transmission cable **20** (see FIG. 1) that is described later from an unshown controller to the ultrasound elements **6**. Note that the respective GND electrodes **15** constitute an acoustic radiation face of the respective ultrasound elements **6**. That is, in each ultrasound element **6**, the GND electrode **15** is provided in a direction that faces the site to be examined.

In addition, in the lens **2**, the acoustic matching layer **11** is provided at a more frontward position in the ultrasound radiation direction **P** than the GND electrode **15**, and the acoustic

matching layer 12 is provided at a more frontward position in the ultrasound radiation direction P than the acoustic matching layer 11.

In this case, with respect to the substrate 5, various operations are performed while the substrates remain in a large state because, since a holding property with respect to the substrates is favorable when the substrates are in a large state, it is easy to perform various operations when electrically connecting the ultrasound elements 6 and the signal wiring lands 5s by means of the signal wiring wires 7 or when forming the lens 2 or the like. Thereafter, the substrates are cut into a certain size so that each substrate 5 can be compactly housed inside a transducer case 70 (see FIG. 3) that is described later.

At the time of the aforementioned cutting operation, as shown in FIG. 3, when cutting is performed so that a lower end site 5u of the substrate 5 that is located in the vicinity of a site to which a distal end of a flexible substrate 21 that is described later is connected is positioned at a higher position in the diameter direction R than an end face 2v on an underside in FIG. 3 of the lens 2, that is, so as to position the lower end site 5u of the substrate 5 on the inner side so as to make the respective substrates 5 as small as possible, there have been cases in which a blade of an apparatus that cuts the substrates 5 strikes against the lens 2 and damages the lens 2. Hence, a configuration is desirable that can make the substrate 5 as small as possible without causing damage to the lens 2.

Therefore, according to the present embodiment, a cutting-plane line e that is used for forming the lower end site 5u of the substrate 5 is inclined at a predetermined angle with respect to the insertion direction S. More specifically, the cutting-plane line e is inclined at a predetermined angle so that an extension line towards the front in the insertion direction S of the cutting-plane line e is positioned so as to be lower than an extension line 2t of the end face 2v on the underside of the lens 2, and an extension line towards the rear in the insertion direction S of the cutting-plane line e is positioned so as to be higher than the extension line 2t of the end face 2v on the underside of the lens 2. That is, a configuration is adopted in which the lower end site 5u of the substrate 5 is formed by cutting the substrate 5 along the cutting-plane line e that is inclined at a predetermined angle.

Therefore, because the blade of the cutting apparatus does not contact the lens 2 and, in addition, the lower end site 5u after cutting can be positioned, as much as possible, at a higher position than the end face 2v on the underside of the lens 2, that is, can be positioned on the inner side in the diameter direction R, the substrate 5 can be formed as small as possible, and hence a reduction in the size of the ultrasound transducer 1 can be achieved.

Further, as shown in FIG. 4 and FIG. 5, at an area that protrudes to the rear in the ultrasound radiation direction P from the backing material frame 10 of the substrate 5, the GND wiring lands 5g are formed on both faces on which the signal wiring lands 5s are formed facing the respective side boards 4.

One end of each of a plurality of connection wires 8 is electrically connected by a solder or the like to the GND wiring lands 5g of the substrate 5. The other end of each of the plurality of connection wires 8 is electrically connected by a solder or the like to a conductive film 91 that is formed by attaching copper foil or the like to the surface of an area that protrudes from the lens 2 of each end board 3.

More specifically, each GND wiring land 5g of the substrate 5 is electrically connected to the conductive film 91 through the connection wires 8. Thus, the configuration is one in which the end boards 3 are grounded. Note that, although

not shown in the drawings, the conductive film 91 is also formed at the side boards 4, and the side boards 4 are also grounded.

Note that, conventionally, with respect to the electrical connection of the other end of the respective connection wires 8 to the conductive film 91 of each end board 3, a configuration has been used in which a through-hole is provided in each end board 3, and the other end of each connection wire 8 is electrically connected by a solder or the like to the conductive film 91 inside the through-hole. However, according to that conventional configuration, since it is necessary to perform connection work inside the through-holes, there is the drawback that it is difficult to perform the connection work and that the connection strength is weak.

Therefore, according to the present embodiment, as shown in FIG. 4 and FIG. 5, a configuration is used in which, at the area that protrudes from the lens 2 of each end board 3, a plurality of concave portions 3h that penetrate the relevant end board 3 along an extending direction of the GND wiring lands 5g as shown in FIG. 4 are provided in a rear end face in the ultrasound radiation direction P, and at a bottom face 3ht of each of the concave portions 3h, the other end of each connection wire 8 is electrically connected by a solder or the like to the conductive film 91 that is formed on the bottom face 3ht. Hence, a configuration is used in which the other end of each connection wire 8 can be electrically connected to the conductive film 91 easily and securely from the rear in the ultrasound radiation direction P.

Further, as shown in FIG. 3, at an area that protrudes to the rear in the ultrasound radiation direction P from the backing material frame 10 of the substrate 5, distal ends of flexible substrates 21 and 22 are electrically connected to each signal wiring land 5s and GND wiring land 5g of the substrate 5, and a distal end of the signal transmission cable 20 that is used to transfer at least electric power and electrical signals to and from the ultrasound elements 6 is electrically connected to the proximal end side of each of the flexible substrates 21 and 22.

Hereunder, a structure in which the flexible substrates 21 and 22 are connected to the ultrasound transducer 1, and the signal transmission cable 20 is connected to the flexible substrates 21 and 22 is referred to as "ultrasound transducer module 60."

More specifically, as shown in FIG. 9, at a position that is more forward in the insertion direction S than the distal ends of two of the flexible substrates 22, the distal ends of two of the flexible substrates 21 are electrically connected in the vicinity of the above described lower end site 5u of the substrate 5 to signal wiring lands 5s on both faces that face the side boards 4 at the area that protrudes from the backing material frame 10 of the substrate 5.

This is because when a configuration is used in which the respective distal ends of the flexible substrates 21 and 22 are electrically connected on both faces of the substrate 5, even if a number of signal lines 21b and 22b (see FIG. 10) that are described later of the flexible substrates 21 and 22 increases, the size of the ultrasound transducer module 60 can be reduced in comparison to a configuration in which the respective distal ends of the flexible substrates 21 and 22 are electrically connected on only one face of the substrate 5.

Further, as shown in FIG. 9, the distal ends of the flexible substrates 22 are electrically connected to the signal wiring lands 5s of the substrate 5 so that rear ends of the flexible substrates 21 overlap only at a region M in the insertion direction S with the distal ends of the flexible substrates 22.

The reason for adopting this configuration is that the ultrasound transducer module 60 can be shortened in the insertion direction S by providing the overlapping region M. That is,

this configuration is adopted to enable a reduction in the size of the ultrasound transducer module **60**.

In other words, if a configuration is used in which the overlapping region M is not provided, and which electrically connects the distal ends of the flexible substrates **21** to the signal wiring lands **5s** of the substrate **5** at a position that is more forward in the insertion direction S than the distal ends of the flexible substrates **22**, the length of the ultrasound transducer module **60** will increase in the insertion direction S.

Hence, it is preferable that the overlapping region M can be secured over as long as possible an area in the insertion direction S in order to reduce the size of the ultrasound transducer module **60**.

Next, a specific configuration for connecting the distal ends of the flexible substrates **21** and **22** to the signal wiring land **5s** and the GND wiring lands **5g** on both faces of the substrate **5** is described using FIG. **10** and FIG. **11**. Note that, to simplify the drawings, FIG. **10** and FIG. **11** illustrate a configuration in which the distal ends of flexible substrates **21** and **22** are connected to one face of the substrate **5**.

As shown in FIG. **10** and FIG. **11**, the flexible substrates **21** and **22** are formed from five layers that include resin layers **21a** and **22a**, a layer in which the signal lines **21b** and **22b** are formed that is formed on one face of the resin layer **21a**, resin layers **21c** and **22c** formed on a face on an opposite side to the resin layers **21a** and **22a** of the signal lines **21b** and **22b**, a layer in which GND lines **21d** and **22d** are formed that is formed on an opposite side to the signal lines **21b** and **22b** of the resin layers **21c** and **22c**, and resin layers **21e** and **22e** formed on an opposite side to the resin layers **21c** and **22c** of the GND lines **21d** and **22d**. Note that the resin layers **21a**, **22a**, **21e**, and **22e** constitute an outer covering of the respective flexible substrates **21** and **22**.

Further, the reason the layer with the GND lines **21d** and **22d** is provided in the flexible substrates **21** and **22**, respectively, is to use the GND lines **21d** and **22d** to prevent the generation of so-called "crosstalk" that is the unintended exchange of signals between the signal lines **21b** and **22b** and the signal wire layer **5s** that may occur if the signal lines **21b** and **22b** are adjacent to the signal wire layer **5s** of the substrate **5**.

More specifically, by providing the GND lines **21d** and **22d**, as shown in FIG. **10**, not only can the signal lines **21b** and **22b** be sufficiently separated by the amount of a space H from the signal wire layer **5s**, but in addition, because the GND lines **21d** and **22d** are grounded, it is difficult for crosstalk to arise between the signal lines **21b** and **22b** and the signal wire layer **5s**. That is, the GND lines **21d** and **22d** function as a shield layer. It is thereby possible to reduce noise that arises in a display of an ultrasound image that is caused by crosstalk.

A plurality of the signal lines **21b** and **22b** protrude forward as flying leads **21bf** and **22bf** from the respective distal ends of the flexible substrates **21** and **22**. As shown in FIG. **9** and FIG. **10**, each of the flying leads **21bf** and **22bf** is electrically connected by a solder **99** to the signal wire layer **5s** that serves as the respective signal wiring lands **5s** of the substrate **5**.

Further, as shown in FIG. **11**, the GND lines **21d** and **22d** also protrude forward as flying leads **21df** and **22df** from the respective distal ends of the flexible substrates **21** and **22**. Each of the flying leads **21df** and **22df** is electrically connected by an unshown solder or the like to the GND wire layer **5g** that serves as a GND wiring land of the substrate **5**.

According to this configuration, the distal ends of the flexible substrates **21** and **22** are connected to the signal wiring lands **5s** and the GND wiring lands **5g** on both faces of the substrate **5**.

In addition, as shown in FIG. **9**, distal ends of the signal transmission cable **20** are electrically connected to the rear ends of the flexible substrates **21** and **22**, respectively, by solders **23** and **24**.

More specifically, the signal transmission cable **20** includes a plurality of cables, and as shown in FIG. **8**, each cable is constituted by a coaxial line in which a resin jacket **20b** is covered over the outer circumference of a signal wire **20a**, a GND wire **20c** is covered over the outer circumference of the resin jacket **20b**, and a resin jacket **20d** is covered over the outer circumference of the GND wire **20c**.

As shown in FIG. **7**, each coaxial line of the signal transmission cable **20** has a configuration in which, at the distal end in the insertion direction S of the signal transmission cable **20**, the GND wire **20c** protrudes forward in the insertion direction S more than the distal end in the insertion direction S of the resin jacket **20d**, the distal end in the insertion direction S of the resin jacket **20b** protrudes forward in the insertion direction S more than the distal end in the insertion direction S of the GND wire **20c**, and the distal end in the insertion direction S of the signal wire **20a** protrudes forward in the insertion direction S more than the distal end in the insertion direction S of resin jacket **20b**.

Each of the protruding signal wires **20a** is electrically connected by a solder **23** or **24** or the like to a pattern of the signal lines **21b** and **22b** of the flexible substrates **21** and **22**. Further, each of the protruding GND wires **20c** is electrically connected by an unshown solder or the like to a pattern of the GND lines **21d** and **22d** of the flexible substrates **21** and **22**. Thus, the respective distal ends of the signal transmission cable **20** are electrically connected to the rear ends of the flexible substrates **21** and **22**.

Hence, the signal transmission cable **20** has a function that transfers various kinds of electrical signals or electric power to and from the ultrasound elements **6** through the signal lines **21b** and **22b** of the flexible substrates **21** and **22** and the signal wiring lands **5s**, the signal wiring wires **7**, and the signal electrodes **16** of the substrate **5**.

Further, the signal transmission cable **20** is also grounded together with the conductive film **91** of the backing material frame **10** through the GND wires **20c**, the GND lines **21d** and **22d**, the GND wiring lands **5g** and the connection wires **8**.

As shown in FIG. **1** and FIG. **3**, the ultrasound transducer module **60** that has the above described configuration is held by the transducer case **70** inside the distal end rigid member **40**. Note that the transducer case **70** is made from, for example, resin.

Further, inside the transducer case **70**, a metal shield member **30** is provided so as to cover the outer circumference of the substrate **5**. A distal end side in the insertion direction S of the metal shield member **30** is fixed by an adhesive **55** composed of, for example, an insulating resin or the like to the transducer case **70** and the lens **2**.

Further, the metal shield member **30** is fixed to the substrate **5** by an adhesive **65** composed of, for example, an insulating resin or the like that is filled inside a large-diameter portion **30a** that is described later of the metal shield member **30**.

Note that, in the present embodiment, a structure in which the metal shield member **30** and the transducer case **70** are provided in the ultrasound transducer module **60** is taken to be the ultrasound transducer unit **50**.

The metal shield member **30** is formed from a cylindrical member. As shown in FIG. **3** and FIG. **6**, the metal shield member **30** includes, as principal components, a large-diameter portion **30a** having a diameter of R**10**, a small-diameter portion **30b** that has a diameter of R**11** that is smaller than the diameter of the large-diameter portion (R**11**<R**10**) and that is

positioned more to the rear than the large-diameter portion **30a** in the direction in which the ultrasound elements **6** and the signal transmission cable **20** are connected, that is, in the insertion direction **S**, and a step portion **30c** that connects the large-diameter portion **30a** and the small-diameter portion **30b** in the insertion direction **S**. In the metal shield member **30**, the large-diameter portion **30a** covers the outer circumference of the substrate **5**, and the small-diameter portion **30b** covers the outer circumference on the distal end side in the insertion direction **S** of the signal transmission cable **20**.

Note that, as the process for providing the metal shield member **30** and the transducer case **70**, a process is used in which, first, the metal shield member **30** is disposed so that the large-diameter portion **30a** covers the outer circumference of the substrate **5** of the ultrasound transducer module **60**, thereafter, the adhesive **65** is filled from the forward side in the insertion direction **S** of the metal shield member **30** to fix the substrate **5** to the large-diameter portion **30a**, and next, the transducer case **70** is covered over the outer circumference of the metal shield member **30** and is fixed to the metal shield member **30** by the adhesive **55**.

However, since there are gaps between the respective coaxial lines of the signal transmission cable **20**, when the adhesive **65** is filled from the front into the metal shield member **30**, there is a possibility that the adhesive **65** will leak from between the coaxial lines of the signal transmission cable **20** and generate a cavity inside the large-diameter portion **30a**.

Hence, according to present embodiment, as shown in FIG. **3**, when covering the metal shield member **30** over the outer circumference of the ultrasound transducer module **60**, a process is used in which the metal shield member **30** and the outer circumference of an area that is inserted into the metal shield member **30** of the signal transmission cable **20** are temporarily fixed in advance using an adhesive **53** for temporary fixing such as a quick-drying adhesive or a high-viscosity adhesive, and thereafter the adhesive **65** is filled from the front into the metal shield member **30**.

More specifically, the ultrasound transducer unit **50** has a configuration in which the metal shield member **30** and the outer circumference of an area that is inserted into the metal shield member **30** of the signal transmission cable **20** are adhesively fixed together by the adhesive **53**.

Note that an adhesive that contains metal filler that is not electrically conductive (SiO_2 , Al_2O_3 , CaCO_3) or the like may be used as the adhesive **53** for temporary fixing.

According to this configuration, a gap does not arise between the metal shield member **30** and the signal transmission cable **20**, and hence, in the process thereafter, even when the adhesive **65** is filled into the metal shield member **30**, the adhesive **65** does not leak out from between the coaxial lines of the signal transmission cable **20**. Thus, in this configuration, the adhesive **65** fixes the metal shield member **30** while reliably ensuring insulation of the substrate **5**.

Further, as shown in FIG. **1**, the large-diameter portion **30a** of the metal shield member **30** has a maximum diameter portion **30am** on the distal end side in the insertion direction **S**.

Note that since an area on the ultrasound elements **6** side of the substrate **5** is large because the central axis **d** in the array direction of the ultrasound elements **6** is inclined, the maximum diameter portion **30am** is formed in the large-diameter portion **30a** to cover the aforementioned large area of the substrate **5**.

In this case, there was the problem that if the central axis of the maximum diameter portion **30am** and a central axis **20i** of the signal transmission cable **20** and another area of the large-

diameter portion **30a** are matching, the ultrasound transducer unit **50** will increase in the diameter direction **R** by an amount corresponding to the size of the maximum diameter portion **30am**, and in addition, a dead space will arise between the ultrasound transducer unit **50** and another member inside the distal end rigid member **40**, and the diameter of the distal end rigid member **40** will increase.

Hence, according to the present embodiment, the maximum diameter portion **30am** is provided inside the transducer case **70** so that, in the diameter direction **R**, a central axis **30i** is shifted to a lower side in FIG. **1** than the central axis **20i** of the signal transmission cable **20** and another area of the large-diameter portion **30a**.

Thus, inside the distal end rigid member **40**, a dead space that arises between the ultrasound transducer unit **50** and another member is decreased, and hence, even when the maximum diameter portion **30am** is provided in the large-diameter portion **30a**, the diameter **R1** of the distal end rigid member **40** can be reduced without changing the diameter **R2** on the distal end side in the insertion direction **S** of the ultrasound transducer unit **50**.

The description will now return to FIG. **3** and FIG. **6**. As shown in FIG. **3** and FIG. **6**, an opening portion **33** is formed in the step portion **30c** of the large-diameter portion **30a** of the metal shield member **30**. Note that a configuration may also be adopted in which the opening portion **33** is formed in only the small-diameter portion **30b**.

Inside the large-diameter portion **30a**, one end **35s** of the ground wiring **35** is electrically connected by a solder or the like to the GND wiring land **5g** of the substrate **5**. The other end **35k** of the ground wiring **35** extends to outside the large-diameter portion **30a**, that is, to outside the metal shield member **30**, through the opening portion **33** and is electrically connected by a solder **32** or the like to an outer circumferential face **30g** on an opposite side to an inner surface **30n** of the small-diameter portion **30b**. As a result, the metal shield member **30** is grounded.

Note that, since the metal shield member **30** is securely grounded, even if the adhesive **55** that is adhered to the end face **2v** of the lens **2** becomes detached therefrom and an electrically conductive fluid such as water that contains impurities from inside the body enters into the transducer case **70**, since the configuration is such that it is easy for the electrically conductive fluid to come in contact with the grounded metal shield member **30** before contacting conducting portions inside the ultrasound transducer unit **50**, such as connection portions between the substrate **5** and the flexible substrates **21** and **22**, the electrical safety is secured.

Note that, in view of this fact, it is desirable that the above described backing material frame **10** is also grounded, and not only the metal shield member **30**. This is because a fluid that enters from the vicinity of the end face **2v** of the lens **2** will invariably come in contact with the backing material frame **10**.

Therefore, as described above, since the conductive film **91** is formed on the backing material frame **10**, and the conductive film **91** is electrically connected through the connection wires **8** with the GND wiring lands **5g** of the substrate **5**, the present embodiment has a configuration in which the backing material frame **10** is grounded.

In addition, with respect to the grounding structure of the metal shield member **30**, as shown in FIG. **13**, a configuration has conventionally been used in which the cylindrical metal shield member **30** covers as far as a proximal end in the insertion direction **S** of the substrate **5** and the other end **35k** of the ground wiring **35** that has the one end **35s** electrically connected to the GND wiring land **5g** of the substrate **5** is

routed as far as the outer circumferential face 30g of the metal shield member 30 from an opening at the proximal end in the insertion direction S of the metal shield member 30, and is electrically connected by a solder 32 or the like to the outer circumferential face 30g.

Hence, according to the above described configuration that is shown in FIG. 13, since it is necessary to secure space inside the transducer case 70 for a connection site between the other end 35k of the ground wiring 35 and the outer circumferential face 30g of the metal shield member 30, there has been the problem that a diameter R9 of the inner surface of the transducer case 70 in the diameter direction R increases by an amount corresponding to the space required for the connection site, that is, the size of the ultrasound transducer unit 50 increases in the diameter direction R.

However, in the configuration shown in FIG. 3, since the other end 35k of the ground wiring 35 is led out to outside the metal shield member 30 through the opening portion 33 from inside the large-diameter portion 30a, and the other end 35k is electrically connected to the small-diameter portion 30b that has a smaller diameter than the large-diameter portion 30a, a diameter R3 of the inner surface of the transducer case 70 in the diameter direction R can be made smaller than the diameter R9 of the inner surface of the transducer case 70 shown in FIG. 13 (R3<R9). More specifically, the diameter of the ultrasound transducer unit 50 can be made smaller than the diameter shown in FIG. 13.

The metal shield member 30 ensures the electrical insulation of various connection sites by covering the outer circumference of the above described connection sites between the substrate 5 and the distal ends of the respective flexible substrates 21 and 22 and the above described connection sites between the distal ends of the signal transmission cable 20 and the respective flexible substrates 21 and 22, together with the insulating adhesive 65.

As shown in FIG. 12, inside a transducer case 70 in an ultrasound transducer unit 50', by making a wall thickness R16 of the transducer case 70 greater than a wall thickness R15 of the transducer case 70 shown in FIG. 3 (R15<R16), the electrical insulation can be ensured even without covering the outer circumference of the substrate 5 with the metal shield member 30, and the withstand voltage performance can be improved.

However, in the configuration shown in FIG. 12, since the outer diameter R4 of the ultrasound transducer unit 50' becomes larger in the diameter direction R than the outer diameter R2 of the ultrasound transducer unit 50 in the configuration using the metal shield member 30 as shown in FIG. 3 (R2<R4), the configuration shown in FIG. 12 is not preferable.

More specifically, in the configuration that ensures the electrical insulation of various connection sites with respect to the substrate 5 and the flexible substrates 21 and 22 using the metal shield member 30 as shown in FIG. 3 according to the present embodiment, with respect to the ultrasound transducer 1, since there are no portions that are not covered with a grounded member, a withstand voltage that is required from the viewpoint of electrical safety is low. Hence the wall thickness R15 of the transducer case 70 according to the present embodiment can be formed to be thinner in the diameter direction R than the wall thickness R16 of the transducer case 70 shown in FIG. 12 (R15<R16), and the outer diameter R2 of the ultrasound transducer unit 50 can be made smaller in the diameter direction R than the outer diameter R4 of the ultrasound transducer unit 50' shown in FIG. 12 (R2<R4).

Further, with regard to configurations that do not use the metal shield member 30, as a configuration that ensures elec-

trical safety without thickening the wall thickness of the transducer case 70, a configuration is known in which metal is applied onto the inner surface of the transducer case 70 by coating or plating or the like.

According to this configuration, since the wall thickness of the transducer case 70 is not made thick, and further, the metal shield member 30 need not be used, the outer diameter of the ultrasound transducer unit 50 can be reduced. However, according to this configuration, at the time of coating or plating, there are cases where the inner surface of the transducer case 70 is subjected to thermal damage, or is subjected to chemical damage that is caused by treatment using a chemical, and therefore the aforementioned configuration is not preferable.

Hence, in the present embodiment a configuration is adopted that uses the metal shield member 30, and it is necessary to form the metal shield member 30 as thinly as possible to prevent the outer diameter of the ultrasound transducer unit 50 increasing due to the metal shield member 30.

In view of the aforementioned circumstances, by forming the metal shield member 30 by a known electroforming process that uses Ni, Cu, Au or the like, as shown in FIG. 15, a wall thickness R6 of the metal shield member 30 can be formed with a uniform film thickness that is thinner than the wall thickness R5 of the metal shield member 30 shown in FIG. 3 (R6<R5). Hence, the outer diameter R7 of the ultrasound transducer unit 50 can be made smaller than the outer diameter R2 of the ultrasound transducer unit shown in FIG. 3 (R7<R2). Further, since it is not necessary to perform plating or the like with respect to the inner surface of the transducer case 70, damage is not caused to the transducer case 70.

In addition, if the metal shield member 30 is formed by an electroforming process, the metal shield member 30 can be formed in a small size, and can be precisely formed in a manner in which there are few dimensional configurations.

Thus, according to the present embodiment a configuration has been described in which, in the ultrasound transducer unit 50, the metal shield member 30 that covers the outer circumference of the substrate 5 inside the transducer case 70 includes the large-diameter portion 30a, the small-diameter portion 30b, and the step portion 30c. Further, in the aforementioned configuration, the metal shield member 30 is grounded by leading out the other end 35k of the ground wiring 35 having the one end 35s electrically connected to the GND wiring land 5g of the substrate 5 to outside the metal shield member 30 from inside the large-diameter portion 30a through the opening portion 33 that is formed in the step portion 30c or the small-diameter portion 30b and electrically connecting the other end 35k to the outer circumferential face 30g of the small-diameter portion 30b that has a smaller diameter than the large-diameter portion 30a.

According to this configuration, by electrically connecting the other end 35k to the outer circumferential face 30g of the small-diameter portion 30b, accompanying the connection of the other end 35k to the metal shield member 30, the connection site of the other end 35k does not protrude to the outer side in the diameter direction R more than the large-diameter portion 30a that has the largest diameter within the metal shield member 30. Hence, as shown in FIG. 3, the diameter R3 of the inner surface of the transducer case 70 in the diameter direction R can be made smaller than the diameter R9 of the inner surface of the transducer case 70 shown in FIG. 13 that has been conventionally used (R3<R9). That is, the outer diameter of the ultrasound transducer unit 50 can be made smaller than the outer diameter of the conventional ultrasound transducer unit that is shown in FIG. 13.

In addition, inside the transducer case **70**, the metal shield member **30**, together with the insulating adhesive **65**, covers the connection sites of the flexible substrates **21** and **22** with respect to the substrate **5** and the connection sites of the signal transmission cable **20** with respect to the flexible substrates **21** and **22** in a reliable manner. Hence, the electrical insulation of the various connection sites can be ensured.

As described above, the ultrasound transducer unit **50** is provided, for example, in the ultrasound endoscope **100**. Hereunder, the configuration of the ultrasound endoscope in which the ultrasound transducer unit **50** is provided is described using FIG. **16**.

FIG. **16** is a view that shows the outer appearance of an ultrasound endoscope in which the ultrasound transducer unit shown in FIG. **3** is provided.

The principal components of the ultrasound endoscope **100** include an elongated insertion portion **110** that is inserted into a subject, an operation portion **103** provided at a proximal end in the insertion direction S of the insertion portion **110**, a flexible universal cord **104** that extends from the operation portion **103**, and a connector **105** that is provided at an extending end of the universal cord **104**.

A light source connector **105a**, an electrical connector **105b**, an ultrasound connector **105c**, a suction pipe sleeve **105d**, and an air/water supply pipe sleeve **105e** are provided in the connector **105**.

A light source apparatus that supplies illuminating light is detachably connected to the light source connector **105a**, and a video processor that performs various kinds of signal processing and the like is detachably connected through a signal cable to the electrical connector **105b**.

Further, an ultrasound observation apparatus is detachably connected to the ultrasound connector **105c** through an ultrasound cable **106** that is connected to the ultrasound observation apparatus. A suction pump is detachably connected through a suction tube to the suction pipe sleeve **105d**. In addition, a water supply tank is detachably connected through an air/water supply tube to the air/water supply pipe sleeve **105e**.

The insertion portion **110** includes a distal end portion **111**, a bending portion **112** that is configured to be bendable in, for example, in the vertical and lateral directions, and a flexible tube portion **113** that is long and has flexibility. The aforementioned portions are connected in series in that order from the distal end side in the insertion direction S of the insertion portion **110**.

The signal transmission cable **20** that is extended from the flexible substrates **21** and **22** of the ultrasound transducer **1** at the distal end portion **111** is inserted through the insertion portion **110**, the operation portion **103**, and the universal cord **104** as far as the ultrasound connector **105c** of the connector **105**, and is electrically connected to the ultrasound cable **106** by the ultrasound connector **105c**.

Note that, the configuration of the ultrasound endoscope **100** that is shown in FIG. **16** as described above is merely one example, and the present invention is not limited thereto.

Thus, the ultrasound transducer unit **50** and the ultrasound endoscope **100** can be provided that can ensure electrical safety and in which a smaller diameter can be realized.

Note that although according to the foregoing embodiment an example is described in which the signal transmission cable **20** is electrically connected to the substrate **5** through the flexible substrates **21** and **22**, a configuration may also be adopted in which the signal transmission cable **20** is electrically connected to the substrate **5** directly, without using the flexible substrates **21** and **22**.

Further, although according to the foregoing embodiment an example is described in which the ultrasound elements **6** are used as the ultrasound elements in an ultrasound transducer, a configuration may also be adopted in which a capacitive micromachined ultrasonic transducer (C-MUT) element that includes a pair of electrodes that face each other in a manner that sandwiches an air gap therebetween is used instead of the ultrasound element **6**.

What is claimed is:

1. An ultrasound transducer unit, comprising:
 - an ultrasound element;
 - a substrate having one end that is electrically connected to the ultrasound element;
 - a signal transmission cable that is electrically connected to the other end of the substrate;
 - a cylindrical metal shield member having a large-diameter portion, a small-diameter portion that has a smaller diameter than a diameter of the large-diameter portion, and a step portion that connects the large-diameter portion and the small-diameter portion, in which an opening portion is formed in the step portion or the small-diameter portion, and in which the large-diameter portion covers an outer circumference of the substrate; and
 - ground wiring that electrically connects the substrate and an outer circumferential face of the metal shield member on an opposite side to an inner surface that faces the substrate;
 wherein,
 - the ground wiring electrically connects the substrate and the outer circumferential face of the metal shield member by being extended to outside the metal shield member from inside the large-diameter portion of the metal shield member through the opening portion and electrically connected to the outer circumferential face of the small-diameter portion.

2. The ultrasound transducer unit according to claim **1**, wherein, the large-diameter portion is positioned further to the ultrasound element side than the small-diameter portion in a direction in which the ultrasound element and the signal transmission cable are connected by the substrate.

3. An ultrasound endoscope, comprising the ultrasound transducer unit according to claim **1** at a distal end in an insertion direction of an insertion portion that is inserted into a subject.

* * * * *

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摘要(译)

超声换能器单元包括：超声元件；基质；信号传输电缆；圆柱形金属屏蔽构件，具有大直径部分，小直径部分和台阶部分，其中大直径部分覆盖基板的外周；接地布线，其电连接基板和金属屏蔽构件的外周面；开口部分形成在台阶部分或小直径部分中。接地布线从大直径部分的内部通过开口部分延伸到金属屏蔽构件的外部，并且电连接到小直径部分的外周面，从而电连接基板和外周面。金属屏蔽构件。

